Investigations on the Reduction of Package Densities in Coplanar Circuits

T. Becks and I. Wolff. "Investigations on the Reduction of Package Densities in Coplanar Circuits." 1993 MTT-S International Microwave Symposium Digest 93.2 (1993 Vol. II [MWSYM]): 869-872.

One of the advantages of coplanar circuit design over microstrip design is the possibility to achieve higher package densities. The paper presents a modified method to calculate generalized scattering parameters for neighboured coplanar lines. A full-wave method is used to analyze important parameters as insertion loss, isolation and reflection not only for the coplanar mode but also for the conversion to the coupled slot line mode. Results for various structures on a GaAs-substrate are presented.

❑ Return to main document.